

OE-A Members – Companies



- O** 3DMA (DE)
- A** ABeetle (TW)
A.F. Suter (GB)
Adphos Digital Printing (DE)
Almax (US)
Apeva (DE)
Alpha Assembly Solutions (US)
American Semiconductor (US)
ARM Ltd. (GB)
- B** BASF Coatings Schweiz (CH)
BASF New Business (DE)
Brewer Science (US)
Brückner Maschinenbau (DE)
BST Eltromat International (DE)
- C** CCI Eurolam (DE)
Ceradrop (FR)
Chasm Advanced Materials (US)
Classic Stripes (IN)
Coatema Coating Machinery (DE)
CondAlign (NO)
Continental (DE)
Copprint (IL)
Coruna Printed Electronics (CH)
- D** db-matik (DE)
DoMicro (NL)
Dorey Converting Systems (FR)
Dowa HD Europe (DE)
Dracula Technologies (FR)
DuPont Teijin Films (GB)
- E** E2IP
Eastman Chemical (DE)
Elantas Europe (DE)
Elmeric (DE)
Emde development of light (DE)
Enfucell Flexible Electronics (CN)
Engineered Materials Systems (US)
Eptatech (IT)
Ersa (DE)
Evonik Operations (DE)
Exakt Advanced Technologies (DE)
- F** Felix Böttcher (DE)
Felix Schoeller Holding (DE)
Fleep Technologies (IT)
FlexEnable (GB)
Folex Coating (DE)
FUELIUM (ES)
Fujifilm Dimatix (US)
- G** Genes'Ink (FR)
Greiner Technology & Innovation (AT)
GRT (DE)
Guangdong Juhua Printing (CN)
- H** Heidelberg Printed Electronics (DE)
Heliatek (DE)
Henkel (DE)
Heraeus Deutschland (DE)
Hoffmann + Krippner (DE)
HyPrint (DE)
- I** IBS Precision Engineering (NL)
IEE (LU)
IMAZ Technology (ES)
InovisCoat (DE)
Inoptec (DE)
Interlink Electronics (US)
Is it fresh (DE)
ISORG (FR)
- J** JT International Germany (DE)
JiLin OLED Material Tech (CN)
- K** Kelenn Technology (FR)
Kroenert (DE)
KSG (DE)
- L** Leonhard Kurz Stiftung (DE))
LinkZill (CN)
Liquid Wire (US)
Lohmann (DE)
- M** Manz (DE)
Mitsui Chemicals Europe (DE)
MMP Premium Printing Center (DE)
M-Solv (GB)
Masar Printing and Publishing (AE)
Masterpress (PL)
Matti Technology (CH)
Merck (DE)
MSW (DE)
- N** Nanorbital Advanced Materials (IN)
NeuDrive (GB)
New Cable Corporation (FI)
NovaCentrix (US)
nsm Norbert Schläfli (CH)
NXT (DE)
- O** OLEDWorks (DE)
Organic Electronic Technologies (GR)
Oxford Photovoltaics (GB)
- P** Papierfabrik Louisenenthal (DE)
Piezotech (FR)
Plastic Logic Germany (DE)
Policrom Screens (IT)
PolyIC (DE)
PragmatlC Semiconductor (GB)
Printcolor Deutschland (DE)
Printed Electronics (GB)
Pütz Folien (DE)
- Q** Quad Industries (BE)
- R** Raynergy Tek (TW)
RK Siebdrucktechnik (DE)
ROWO Coating (DE)
- S** SABIC (NL)
SAES Getters (IT)
SAIT Europe (GB)
Saralon (DE)
Saueressig (DE)
Schreiner Group (DE)
Screentec (FI)
Senorics (DE)
- Seqens (FR)
SmartKem (UK)
Smit Thermal Solutions (NL)
Smooth & Sharp Corporation (TW)
Spin Corporation (JP)
SunaTech (CN)
- T** Tacterion (DE)
Tactotek (FI)
Tagenea (ES)
Teknek (GB)
Thin Film Electronics (US)
Toyobo (JP)
TSE Troller (CH)
- V** VARTA Microbattery (DE)
VDL Flow (NL)
- W** Werner Blase (DE)
Witte plusprint (DE)
- X** X-Celeprint (IE)
Xenon Corporation (US)
Xiamen Funano New Material (CN)
Xymox Technologies (US)
- Y** Ynvisible (PT)
YTC America (US)
- Z** ZEON (JP)

- A** AIST – Sensing Electronics Center (JP)
AIT – Austrian Institute of Technology (AT)
AlmaScience (PT)
Aristotle University of Thessaloniki - LTFN (GR)
- B** BRNO University of Technology (CZ)
- C** C2MI (CA)
CEA Liten (FR)
Centi - Centre for Nanotechnology & Smart Materials (PT)
Centre Technique du Papier (CTP) (FR)
CIDETEC (ES)
Consiglio Nazionale delle Ricerche (CNR) (IT)
COPT Center (DE)
CPI - Centre for Process Innovation (GB)
CSEM (CH)
CSIR (ZA)
- E** EMPA (CH)
ESA (GB)
Eurecat (ES)
- F** Fontys University of Applied Sciences (NL)
Fraunhofer ENAS (DE)
Fraunhofer FEP (DE)
Fraunhofer IAP (DE)
Fraunhofer IFAM (DE)
Fraunhofer ILT (DE)
Fraunhofer IPA (DE)
Fraunhofer ISC (DE)
Fraunhofer ISE (DE)
Friedrich-Alexander-Universität – WW6 – i-Meet (DE)
Friedrich Schiller Universität Jena (DE)
- H** Hahn-Schickard-Gesellschaft für angewandte Forschung (DE)
Hochschule der Medien - IAF, IAD (DE)
Hochschule München University of Applied Sciences (DE)
Hochschule Niederrhein (DE)
Holst Centre (NL)
- I** ICI – Printability and Graphic Communications Institute (CA)
IMB-CNM (CSIC) (ES)
Imec (BE)
Imperial College London – Centre for Plastic Electronics (GB)
InnovationLab (DE)
Institut für Mikroelektronik Stuttgart (DE)
Instituto de Tecnología Cerámica (ES)
- IPC** – Technical Centre of Plastics Engineering (FR)
- ITRI** - Industrial Technology Research Institute (TW)
- IUBH** Internationale Hochschule (DE)
- J** Joanneum Research (AT)
Johannes Kepler Universität Linz - LIOS (AT)
- K** Karlsruhe Institute of Technology - LTI (DE)
Konkuk University - FDRC (KR)
- L** Landshut University of Applied Sciences (DE)
Leitat Technological Center (ES)
Loughborough University (GB)
- M** MINES Saint-Étienne – Microelectronics - Center of Provence (FR)
- N** NAITEC (ES)
National Research Council Canada (CA)
NPL - National Physics Laboratory (GB)
- O** Oulu University of Applied Sciences (FI)
- P** Palo Alto Research Center (US)
Papiertechnische Stiftung (DE)
Profactor (AT)
- R** RISE Research Institutes of Sweden (SE)
- T** Tampere University (FI)
Technische Hochschule Nürnberg Georg Simon Ohm (DE)
Technische Universität Chemnitz (DE)
Technische Universität Darmstadt - IDD (DE)
Technische Universität Dresden - IAPP (DE)
Tekniker (ES)
TOPIC – Thailand Organic and Printed Electronic Innovation Center (TH)
- U** University of Applied Sciences Northwestern Switzerland (CH)
University of West Bohemia – RICE (CZ)
University of Bordeaux (FR)
University of Manchester (GB)
University of Novi Sad – Faculty of Technical Sciences (CS)
University of Oulu (FI)
University of Pardubice (CZ)
- V** Vito (BE)
VTT - Technical Research Centre of Finland (FI)
- W** WCPC - Swansea University (GB)
- Y** Yamagata University (JP)